

# Power Inductor

**AHP201610BMV-SERIES**

## 1、 Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
3. High reliability -Reliability tests comply with AEC-Q200

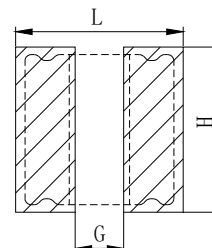
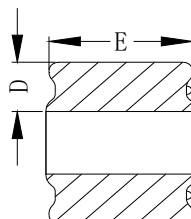
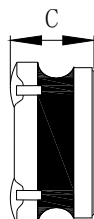
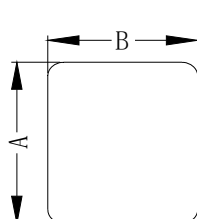


## 2、 Applications

Automotive applications.

### Recommended Land pattern

## 3、 Dimension



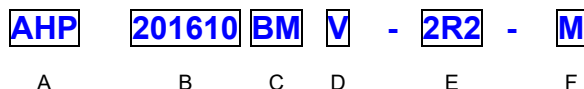
Series	*A(mm)	*B(mm)	*C(mm)	D(mm)	E(mm)
AHP201610	2.0±0.2	1.6±0.2	0.9±0.1	0.7±0.3	1.6±0.2

L(mm)	G(mm)	H(mm)
2.5	0.5	2.0

\*Dimensions are not including the termination. For maximum overall dimensions with termination , add 0.1mm.

Note: 1. The above PCB layout reference only.  
2. Recommend solder paste thickness at 0.10mm and above.

## 4、 Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Code
  - V=Vehicle
- E: Inductance
  - 2R2=2.20uH
- F: Inductance Tolerance
  - K=± 10%, L=± 15%, M=± 20%, Y=± 30%.

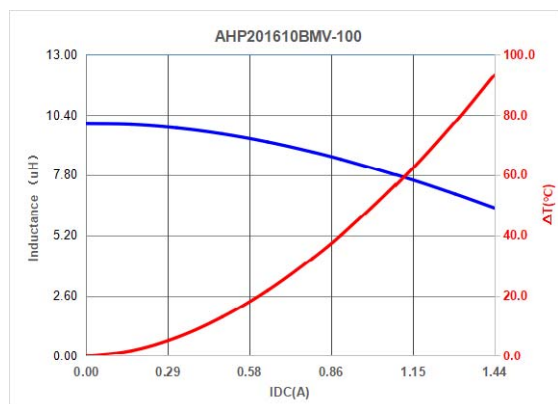
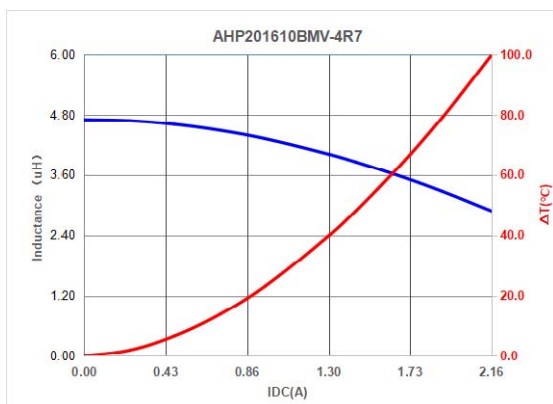
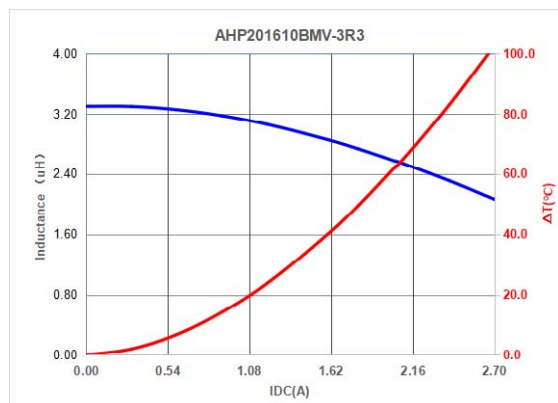
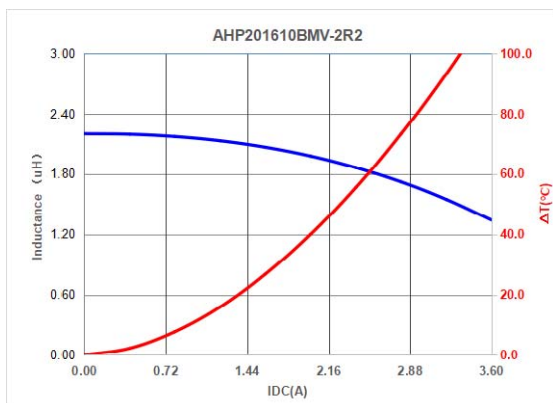
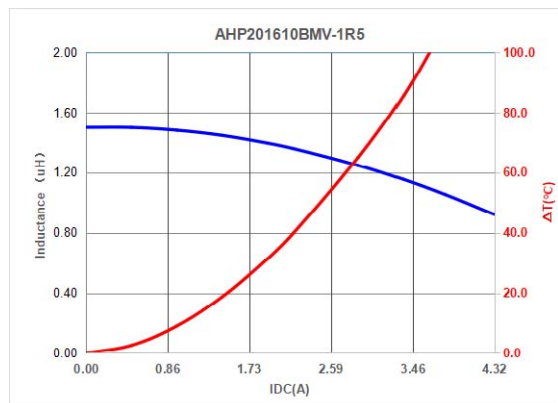
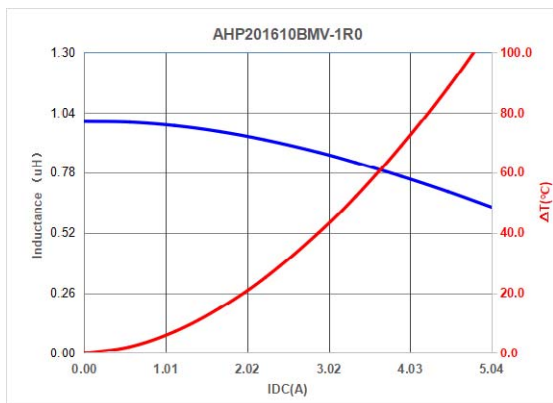
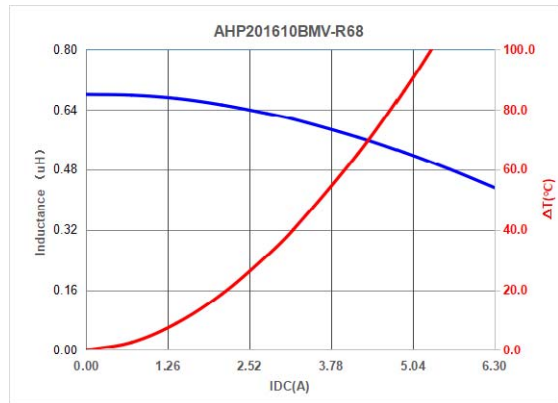
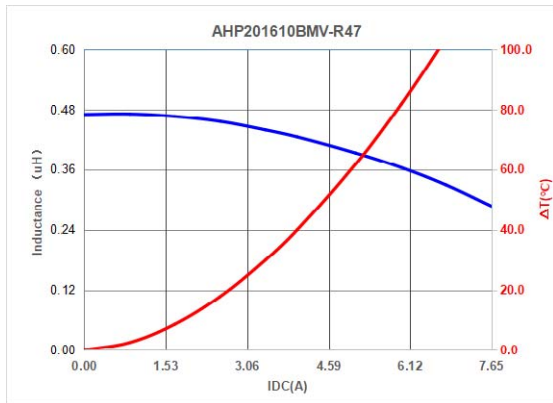
## 5、Specification

TAI-TECH Part Number	Inductance (uH)	I rms (A)		I sat (A)		DCR (mΩ)	
		typ	Max	typ	Max	typ	Max
AHP201610BMV-R47M	0.47	4.00	3.50	6.80	6.20	42	50.4
AHP201610BMV-R68M	0.68	3.20	2.80	5.60	5.00	52	62.4
AHP201610BMV-1R0M	1.00	2.90	2.60	4.50	4.00	75	90
AHP201610BMV-1R5M	1.50	2.20	1.90	3.80	3.40	120	144
AHP201610BMV-2R2M	2.20	2.00	1.70	3.20	2.80	160	196
AHP201610BMV-3R3M	3.30	1.60	1.40	2.40	2.20	240	288
AHP201610BMV-4R7M	4.70	1.30	1.10	1.90	1.70	362	435
AHP201610BMV-100M	10.0	0.90	0.70	1.30	1.10	800	960

Note:

1. Test frequency : Ls : 1MHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately  $\Delta T$  of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃ under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.  
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.

# 11、Typical Performance Curves



单击下面可查看定价，库存，交付和生命周期等信息

[>>TAI-TECH\(台庆\)](#)